

3D IC and 2.5D IC Packaging Market: Trends, Opportunities and Competitive Analysis [2023-2028]

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Abstracts

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3D IC and 2.5D IC Packaging Market Trends and Forecast

The future of the global 3D IC and 2.5D IC packaging market looks promising with opportunities in the consumer electronic, industrial, telecommunication, automotive, military & aerospace, and medical device industries. The global 3D IC and 2.5D IC packaging market is expected to reach an estimated \$81.1 billion by 2028 with a CAGR of 11% from 2023 to 2028. The major drivers for this market are growing demand for miniaturized IoT based devices, emergence of 5G technologies, and the widespread use of high-end computation, servers, and data centers.

A more than 150-page report is developed to help in your business decisions. Sample figures with some insights are shown here.

3D IC and 2.5D IC Packaging Market by Segment

The study includes trends and forecast for the global 3D IC and 2.5D IC packaging market by packaging technology, application, end use industry, and region, as follows:

3D IC and 2.5D IC Packaging Market by Packaging Technology [Shipment Analysis by Value from 2017 to 2028]:

3D Wafer-Level Chip-Scale Packaging (WLCSP)

3D Through-Silicon Via (TSV)

2.5D

3D IC and 2.5D IC Packaging Market by Application [Shipment Analysis by Value from 2017 to 2028]:

Logic

Imaging & Optoelectronics

Memory

MEMS/Sensors

LED

Others

3D IC and 2.5D IC Packaging Market by End Use Industry [Shipment Analysis by Value from 2017 to 2028]:

Consumer Electronics

Industrial

Telecommunications

Automotive

Military & Aerospace

Medical Devices

Others

3D IC and 2.5D IC Packaging Market by Region [Shipment Analysis by Value from 2017

to 2028]:

North America

Europe

Asia Pacific

The Rest of the World

List of 3D IC and 2.5D IC Packaging Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies, 3D IC and 2.5D IC packaging companies cater to increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the 3D IC and 2.5D IC packaging companies profiled in this report include-

Taiwan Semiconductor Manufacturing

Samsung Electronics

Toshiba

Advanced Semiconductor Engineering

Amkor Technology

3D IC and 2.5D IC Packaging Market Insights

Lucintel forecasts that the MEMS/sensor segment is expected to witness the highest growth over the forecast period due to the widespread use of 2.5D and 3D IC packaging in advanced MEMS and miniaturized sensors, such as microphones, accelerometers, gyroscopes, digital compasses, inertial modules, pressure sensors, humidity sensors, and smart sensors.

Consumer electronics is expected to remain the largest segment due to the increasing adoption of 3D IC and 2.5D IC packaging based innovative memories, such as double-data-rate (DDR) DRAM and flash memory in the electronic devices, like smartphones and tablets.

APAC is expected to witness the highest growth over the forecast period due to the huge adoption of electronic gadgets among increasing population, growing demand for ICs from the telecommunication and automotive industries, and the presence of key manufacturers in the region.

Features of the 3D IC and 2.5D IC Packaging Market

Market Size Estimates: 3D IC and 2.5D IC packaging market size estimation in terms of value (\$B)

Trend And Forecast Analysis: Market trends (2017-2022) and forecast (2023-2028) by various segments and regions.

Segmentation Analysis: 3D IC and 2.5D IC packaging market size by various segments, such as by packaging technology, application, end use industry, and region

Regional Analysis: 3D IC and 2.5D IC packaging market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in different packaging technologies, applications, end use industries, and regions for the 3D IC and 2.5D IC packaging market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the 3D IC and 2.5D IC packaging market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

FAQ

Q1. What is the 3D IC and 2.5D IC packaging market size?

Answer: The global 3D IC and 2.5D IC packaging market is expected to reach an estimated \$81.1 billion by 2028.

Q2. What is the growth forecast for 3D IC and 2.5D IC packaging market?

Answer: The global 3D IC and 2.5D IC packaging market is expected to grow with a CAGR of 11% from 2023 to 2028.

Q3. What are the major drivers influencing the growth of the 3D IC and 2.5D IC packaging market?

Answer: The major drivers for this market are growing demand for miniaturized IoT based devices, the emergence of 5G technologies, and the widespread use of high-end computation, servers, and data centers.

Q4. What are the major segments for 3D IC and 2.5D IC packaging market?

Answer: The future of the 3D IC and 2.5D IC packaging market looks promising with opportunities in the consumer electronic, industrial, telecommunication, automotive, military & aerospace, and medical device industries.

Q5. Who are the key 3D IC and 2.5D IC packaging companies?

Answer: Some of the key 3D IC and 2.5D IC packaging companies are as follows:

Taiwan Semiconductor Manufacturing

Samsung Electronics

Toshiba

Advanced Semiconductor Engineering

Amkor Technology

Q6.Which 3D IC and 2.5D IC packaging segment will be the largest in future?

Answer:Lucintel forecasts that MEMS/sensor is expected to witness the highest growth over the forecast period due to the widespread use of 2.5D and 3D IC packaging in advanced MEMS and miniaturized sensors, such as microphones, accelerometers, gyroscopes, digital compasses, inertial modules, pressure sensors, humidity sensors, and smart sensors.

Q7. In 3D IC and 2.5D IC packaging market, which region is expected to be the largest in next 5 years?

Answer: APAC is expected to witness the highest growth over the forecast period due to the huge adoption of electronic gadgets among increasing population, growing demand for ICs in the telecommunication and automotive industries, and presence of key manufacturers in the region.

Q8.Do we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

Q.1. What are some of the most promising, high-growth opportunities for the global 3D IC and 2.5D IC packaging market by packaging technology (3D wafer-level chip-scale packaging (WLCSP), 3D through-silicon via (TSV), and 2.5D), application (logic, imaging & optoelectronics, memory, MEMS/sensors, LED, and others), end use industry (consumer electronics, industrial, telecommunications, automotive, military & aerospace, medical devices, and others), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2. Which segments will grow at a faster pace and why?

Q.3. Which region will grow at a faster pace and why?

Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?

Q.5. What are the business risks and competitive threats in this market?

Q.6. What are the emerging trends in this market and the reasons behind them?

Q.7. What are some of the changing demands of customers in the market?

Q.8. What are the new developments in the market? Which companies are leading these developments?

Q.9. Who are the major players in this market? What strategic initiatives are key players

pursuing for business growth?

Q.10. What are some of the competing products in this market and how big of a threat do they pose for loss of market share by material or product substitution?

Q.11. What M&A activity has occurred in the last five years and what has its impact been on the industry?

For any questions related to 3D IC and 2.5D IC packaging market or related to 3D IC and 2.5D IC packaging companies, 3D IC and 2.5D IC packaging market size, 3D IC and 2.5D IC packaging market share, 3D IC and 2.5D IC packaging market growth, 3D IC and 2.5D IC packaging market research, write Lucintel analyst at email: helpdesk@lucintel.com we will be glad to get back to you soon.

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